

SOT1464-1

WLCSP6, wafer level chip-scale package, 6 bumps, 0.19 mm pitch, 0.57 mm x 0.43 mm x 0.28 mm body

28 December 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP6
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	25-04-2016
Manufacturer package code	SOT1464

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	0.54	0.57	0.6	mm
package width	0.4	0.43	0.46	mm
seated height	0.255	0.28	0.305	mm
package height	0.18	0.2	0.22	mm
nominal pitch	-	0.19	-	mm
actual quantity of termination	-	6	-	



2 Package outline

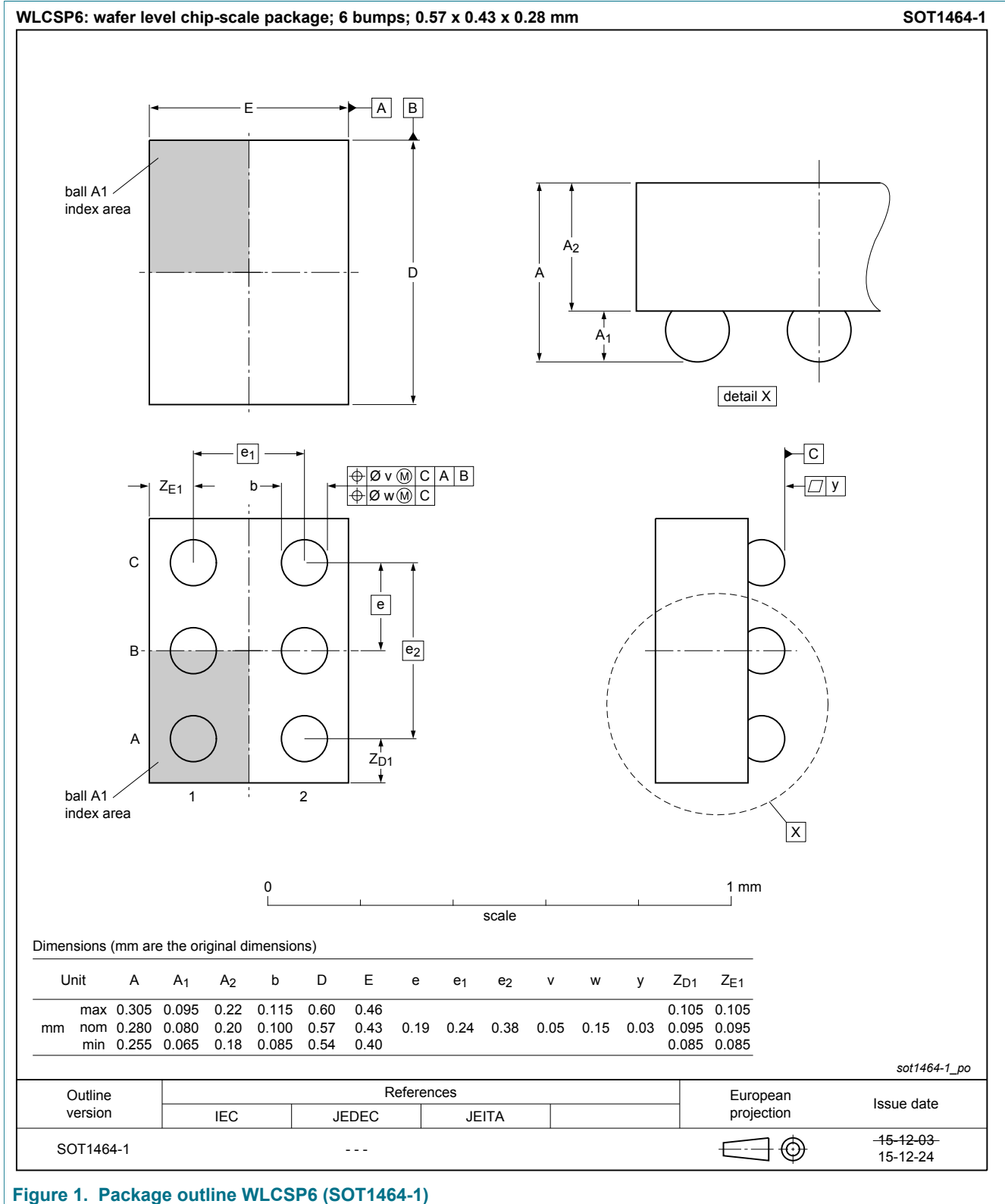


Figure 1. Package outline WLCSP6 (SOT1464-1)

3 Legal information

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